

AMENDED VERSION OF SECTION OF SPECIFICATION

Applicant respectfully requests the substitution of the table below for the table appearing at the top of page 9 of the description of this application as filed.

Application Number	Title of Application	First Named Inventor
09/687,485	Semiconductor Package Having Increased Solder Joint Strength	Kil Chin Lee
09/687,487	Clamp and Heat Block Assembly for Wire Bonding a Semiconductor Package Assembly	Young Suk Chung
09/687,876	Near Chip Size Semiconductor Package	Sean Timothy Crowley
09/687,495	Semiconductor Package	Sean Timothy Crowley
09/687,531	Stackable Semiconductor Package and Method for Manufacturing Same	Sean Timothy Crowley
09/687,530	Stackable Semiconductor Package and Method for Manufacturing Same	Jun Young Yang
09/687,126	Method of and Apparatus for Manufacturing Semiconductor Packages	Hyung Ju Lee
09/687,541	Semiconductor Package Leadframe Assembly and Method of Manufacture	Young Suk Chung

Replacement sheet 9 of the specification is enclosed for the convenience of the Examiner in entering the preceding amendment.



Patent Application
Docket #45475-00028
99-44653

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10 It is thus believed that the operation and construction of the present invention will be apparent from the foregoing description of the preferred exemplary embodiments. It will be obvious to a person of ordinary skill in the art that various changes and modifications may be made herein without departing from the spirit and the scope of the invention.